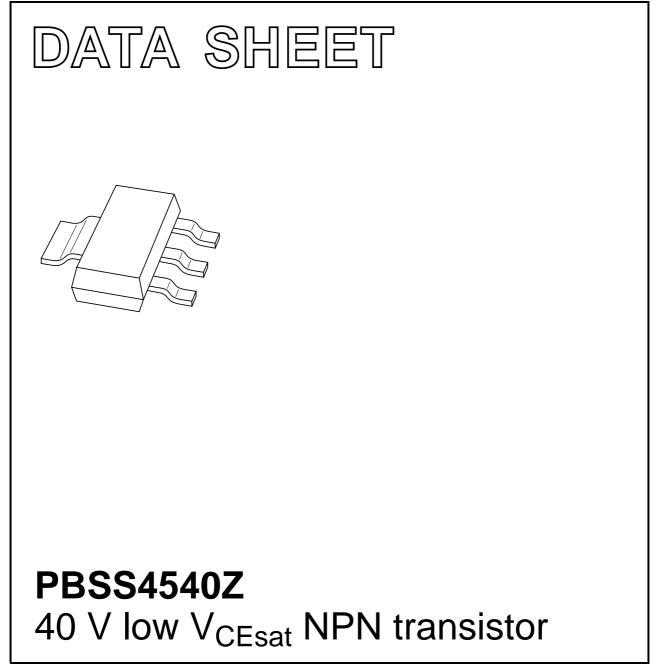
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2001 Jul 24 2001 Nov 14



FEATURES

- Low collector-emitter saturation voltage
- High current capabilities
- Improved device reliability due to reduced heat generation.

APPLICATIONS

- Supply line switching circuits
- Battery management applications
- DC/DC converter applications
- Strobe flash units
- Heavy duty battery powered equipment (motor and lamp drivers)
- MOSFET driver applications.

DESCRIPTION

NPN low V_{CEsat} transistor in a SOT223 plastic package. PNP complement: PBSS5540Z.

MARKING

TYPE NUMBER	MARKING CODE	
PBSS4540Z	PB4540	

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX	UNIT
V _{CEO}	emitter-collector voltage	40	V
I _C	collector current (DC)	5	А
I _{CM}	peak collector current	10	А
R _{CEsat}	equivalent on-resistance	<71	mΩ

PINNING

PIN	DESCRIPTION	
1	base	
2	collector	
3	emitter	
4	collector	

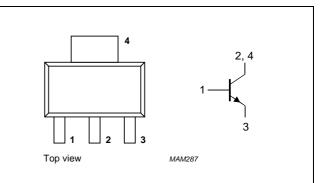


Fig.1 Simplified outline (SOT223) and symbol.

PBSS4540Z

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	40	V
V _{CEO}	collector-emitter voltage	open base	-	40	V
V _{EBO}	emitter-base voltage	open collector	-	6	V
I _C	collector current (DC)		-	5	A
I _{CM}	peak collector current		-	10	A
I _{BM}	peak base current		-	2	A
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; notes 1 and 3	-	1.35	W
		$T_{amb} \le 25 \text{ °C}$; notes 2 and 3	-	2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².
- 2. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 6 cm².
- 3. For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to	note 1	92	K/W
ambient		note 2	62.5	K/W

Notes

- 1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².
- 2. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 6 cm².

PBSS4540Z

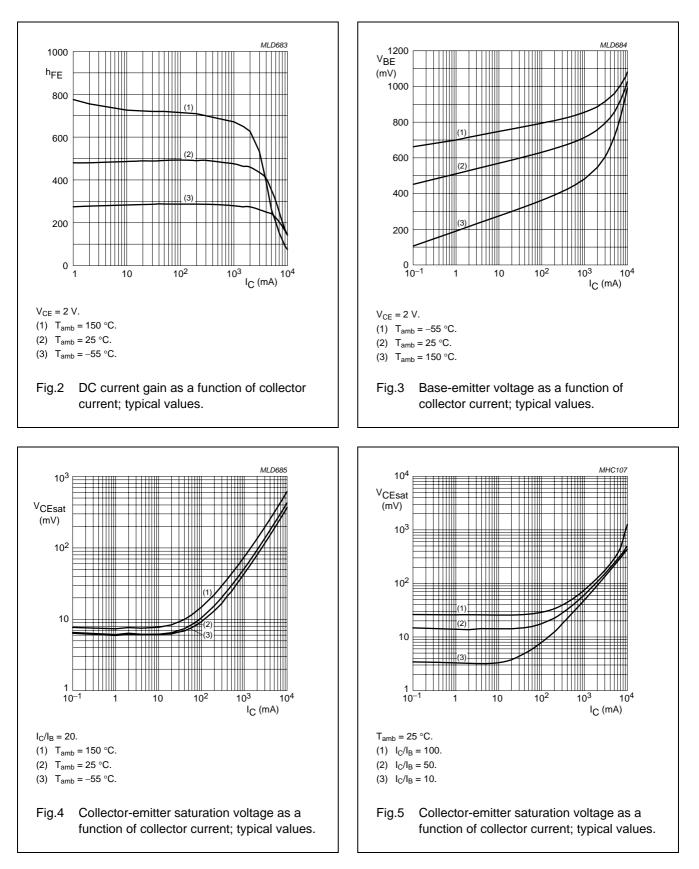
CHARACTERISTICS

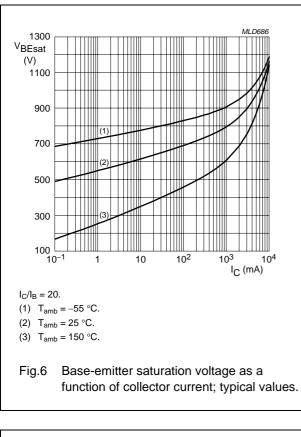
 T_{amb} = 25 °C unless otherwise specified.

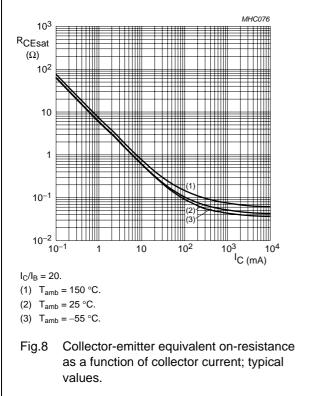
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = 30 \text{ V}; I_E = 0$	_	_	100	nA
		V _{CB} = 30 V; I _E = 0; T _j = 150 °C	-	_	50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0$	—	_	100	nA
h _{FE}	DC current gain	$V_{CE} = 2 \text{ V}; \text{ I}_{C} = 500 \text{ mA}$	300	500	-	
		$V_{CE} = 2 \text{ V}; I_{C} = 1 \text{ A}; \text{ note } 1$	300	500	_	
		$V_{CE} = 2 \text{ V}; I_{C} = 2 \text{ A}; \text{ note } 1$	250	450	-	
		$V_{CE} = 2 \text{ V}; I_{C} = 5 \text{ A}; \text{ note } 1$	100	300	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 500 mA; I _B = 5 mA	-	50	90	mV
		I _C = 1 A; I _B = 10 mA	-	75	120	mV
		I _C = 2 A; I _B = 200 mA	-	90	150	mV
		I _C = 5 A; I _B = 500 mA	-	210	355	mV
R _{CEsat}	equivalent on-resistance	I _C = 5 A; I _B = 500 mA; note 1	-	42	71	mΩ
V _{BEsat}	base-emitter saturation voltage	I _C = 5 A; I _B = 500 mA	_	1.1	1.3	V
V _{BEon}	base-emitter turn-on voltage	V _{CE} = 2 V; I _C =2 A	-	0.8	1.1	V
f _T	transition frequency	I _C = 100 mA; V _{CE} = 10 V; f = 100 MHz	70	130	-	MHz
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0;$ f = 1 MHz	-	60	75	pF

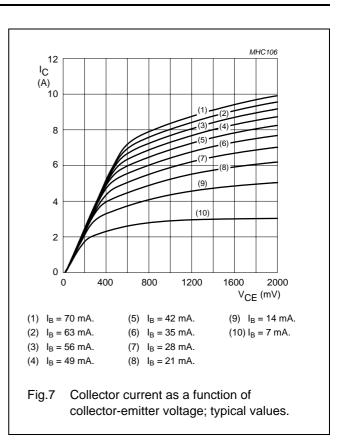
Note

1. Pulse test: $t_p \leq 300~\mu s;~\delta \leq 0.02.$

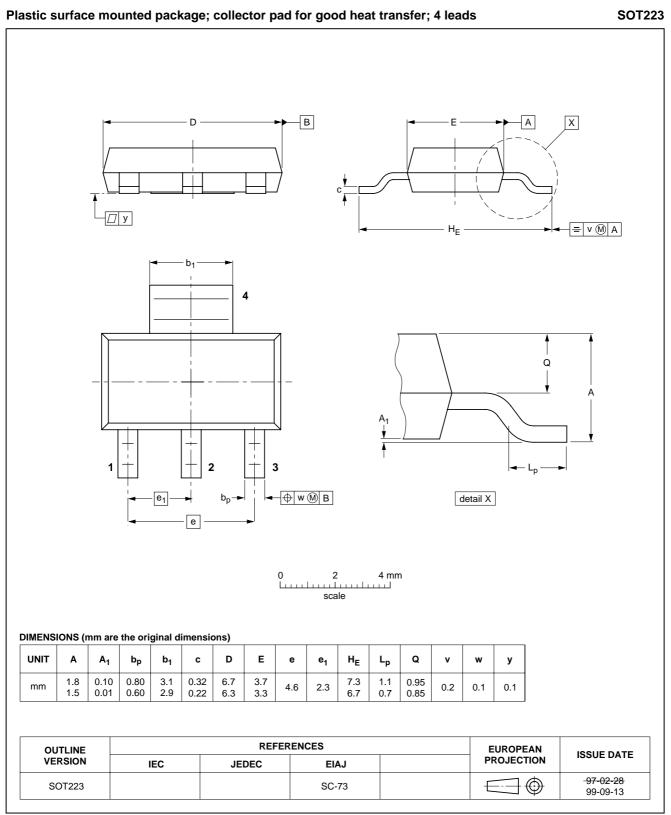








PACKAGE OUTLINE



PBSS4540Z

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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